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**SUPPLEMENTAL
INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)

Sheet 1 of 2

<i>Complete If Known</i>	
<i>Application Number</i>	10/608,404
<i>Filing Date</i>	June 26, 2003
<i>First Named Inventor</i>	Liu, et al.
<i>Art Unit</i>	1742
<i>Examiner Name</i>	Michael P. Alexander
<i>Attorney Docket Number</i>	APPM/005699.P3/PPC/CMP/CKIM

U.S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

**Examiner
Signature**

W. E. L.

**Date
Considered**

12-20-2005

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Sheet

2 of 2

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First Named Inventor	Liu, et al.
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Examiner Name	Michael P. Alexander

Attorney Docket Number APPM/005699.P3/PPC/CMP/CKIM

NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
MPA	C1	Deshpande, et al., "Chemical Mechanical Planarization of Copper: Role of Oxidants and Inhibitors", <i>Journal of The Electrochemical Society</i> , pp. G788-G794 (2004).	
MPA	C2	Economikos, et al., "Integrated Electro-Chemical Mechanical Planarization (Ecmp) for Future Generation Device Technology", 2004 IEEE, pp. 233-235.	
MPA	C3	Goonetilleke, et al., "Voltage-Induced Material Removal for Electrochemical Mechanical Planarization of Copper in Electrolytes Containing NO -3, Glycine, and H2O2", <i>Electrochemical and Solid-State Letters</i> , pp. G190-G193 (2005).	
MPA	C4	Steigerwald, et al., "Effect of Copper Ions in the Slurry on the Chemical-Mechanical Polish Rate of Titanium", <i>J. Electrochem. Soc.</i> , Vol. 141, No. 12, December 1994, pp. 3512-3516.	

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Sheet 1 of 3

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Application Number	10/608,404
Filing Date	JUNE 26, 2003
First Named Inventor	LIU, et al.
Art Unit	1742
Examiner Name	MICHAEL P. ALEXANDER
Attorney Docket Number	AMAT/5699.P3/CMP/CMP/RKK

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ³ (if known)			
MP1	A1	US-6,893,476	5/17/2005	6,893,476	
	A2	US-2001/0016469	8/23/2001	Chopra	
	A3	US-2001/0052351	12/20/2001	Brown, et al.	
	A4	US-2002/0016064	2/7/2002	Komai, et al.	
	A5	US-2002/0130049	9/19/2002	Chen, et al.	
	A6	US-2003/0115475	6/19/2003	Russo, et al.	
	A7	US-2003/0116446	6/23/2003	Duboust, et al.	
	A8	US-2003/0178320	9/25/2003	Liu, et al.	
	A9	US-2003/0216045	12/20/2003	Wang, et al.	
	A10	US-2003/0234184	12/25/2003	Liu, et al.	
	A11	US-2004/0053499	3/18/2004	Liu, et al.	
	A12	US-2004/0144038	07/29/2004	Siddiqui	
	A13	US-2004/0248412	12/9/2004	Liu, et al.	
	A14	US-2005/0044803	3/3/2005	Siddiqui, et al.	
	A15	US-2005/0076578	04/14/2005	Siddiqui, et al.	
	A16	US-2005/0076579	04/14/2005	Siddiqui, et al.	
	A17	US-2005/0079718	04/14/2005	Siddiqui, et al.	
	A18	US-2005/0079803	04/14/2005	Siddiqui, et al.	
	A19	US-2005/0565378	3/17/2005	Chen, et al.	

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
		Country Code ³ - Number ⁴ - Kind Code ⁵ (if known)				
MPQ	B1	EP 0 699 782	3/6/1996	Datta		
MPQ	B2	EP 1 167 585	1/2/2002	Hong		
MPQ	B3	JP 05 302199 (English abstract)	11/16/1993	Bridgestone Bekaert Steel		X
MPQ	B4	JP 06 158397 (English abstract)	6/7/1994	Asahi Glass Co Ltd		X
MPQ	B5	JP 10 121297 (English translation)	5/12/1998	Nippon Riiironaale		X
MPQ	B6	JP 58-093886 (English abstract)	6/3/1983	Tokoyama Soda Co Ltd		X
MPQ	B7	JP 58-093899 (English abstract)	6/8/1983	Sumitomo Metal Land Ltd		X
MPQ	B8	JP 01-77117 (English translation)	3/23/2001	Takeshi, et al.		X
MPQ	B9	JP 2000 192298 (English abstract)	7/11/2000	Ebara		X
MPQ	B10	JP 2000 256898 (English abstract)	9/19/2000	Permelec Electrod Ltd		X
MPQ	B11	SU 1 618 538 (English abstract)	1/7/1991	Vladimir		X
MPQ	B12	WO 02/88229	11/7/2002	Beulich, et al.		
MPQ	B13	WO 02/75804	9/26/2002	Chen		
MPQ	B14	WO 02/23616	3/21/2002	Wang		

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MPQ

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Substitute for form 1449A/PTO				Complete if Known	
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		Filing Date		JUNE 26, 2003	
		First Named Inventor		LIU, et al.	
		Art Unit		1742	
		Examiner Name		MICHAEL P. ALEXANDER	
Sheet	2	of	3	Attorney Docket Number	AMAT/5699.P3/CMP/CMP/RKK

NON PATENT LITERATURE DOCUMENTS				
Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.		
MPQ	C1	International Search Report for PCT/US02/40754 dated August 5, 2003. (AMAT/5998PC)		T ²
MPQ	C2	PCT International Search Report for PCT/US04/17691, dated November 16, 2004. (AMAT/5699.PC03)		
MPQ	C3	PCT Written Opinion for PCT/US04/17691, dated November 16, 2004. (AMAT/5699.PC03)		
MPQ	C4	Besser et al., "Mechanical Strain Evolution in Cu/low K Interconnect Lines", <i>Mat. Res. Soc. Symp. Proc.</i> Vol. 795, 2004 Materials Research Society, pp. U1.1.1-U1.1.6.		
MPQ	C5	Chandrasekaran, et al., "Effects of CMP Process Conditions on Defect Generation in Low-k Materials", <i>Journal of The Electrochemical Society</i> , pp. G882-G889 (2004).		
MPQ	C6	Chang, et al., "Microleveling Mechanisms and Applications of Electropolishing of Planarization of Copper Metallization", <i>J. Vac. Sci. Technol. B</i> 20(5), Sep/Oct 2002, pp. 2149-2152.		
MPQ	C7	Chang, et al., "Superpolishing of Planarizing Copper Damascene Interconnects", <i>Electrochemical and Solid-State Letters</i> , pp. G72-G74 (2003).		
MPQ	C8	Contolini, et al., "Electrochemical Planarization for Multilevel Metallization", <i>J. Electrochem. Soc.</i> , Vol. 141, No. 9, September 1994, pp. 2503-2510.		
MPQ	C9	Du, et al., "Mechanism of Copper Removal During CMP in Acidic H2O2 Slurry", <i>Journal of The Electrochemical Society</i> , pp. G230-235 (2004).		
MPQ	C10	Hu, et al. "Copper Interconnection Integration and Reliability", <i>Thin Solid State Films</i> , pp. 84-92, (1995).		
MPQ	C11	Jin-Hua, et al., "An XPS and BAW Sensor Study of the Structure and Real-Time Growth Behaviors of a Complex Surface Film on Copper in Sodium Chloride Solutions (pH=9), Containing a Low Concentration of Benzotriazole", <i>Eletrochimica Acta</i> , Vol. 43, Nos 3-4, pp. 265-274, 1998.		

Examiner Signature		Date Considered	12-2005
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<i>MPA</i>	C12	Kaufman, et al., "Chemical-Mechanical Polishing for Fabricating Patterned W Metal Features as Chip Interconnects", <i>J. Electrochem. Soc.</i> , Vol. 138, No. 11, November 1991; The Electrochemical Society, Inc. pp. 3460-3465.		
<i>MPA</i>	C13	Kondo, et al., "Role of Additives for Copper Damascene Electrodeposition: Experimental Study on Inhibition and Acceleration Effects", <i>Journal of The Electrochemical Society</i> , pp. C250-C255 (2004)		
<i>MPA</i>	C14	Padhi, et al., "Planarization of Copper Thin Films by Electropolishing in Phosphoric Acid for ULSI Applications", <i>Journal of the Electrochemical Society</i> , 150, pp. G10-G14 (2003).		
<i>MPA</i>	C15	Qafsaoui, et al., "Quantitative Characterization of Protective Films Grown on Copper in the Presence of Different Triazole Derivative Inhibitors", <i>Electrochimica Acta</i> 47 (2002), pp. 4339-4346.		
<i>MPA</i>	C16	Tamilmani, et al., "Potential-pH Diagrams of Interest to Chemical Mechanical Planarization of Copper", <i>Journal of The Electrochemical Society</i> , V. 149, pp. G638-G642 (2002).		
<i>MPA</i>	C17	Tromans, et al., "Growth of Passivating CuBTA Films on Copper in Aqueous Chloride/Benzotriazole Solutions", <i>Electrochemical and Solid-State Letter</i> , V. 5, pp. B5-B8 (2002).		
<i>MPA</i>	C18	Wang, et al., "Inhibition Effect of AC-Treated, Mixed Self-Assembled Film of Phenylthiourea and 1-Dodecanethiol on Copper Corrosion", <i>Journal of The Electrochemical Society</i> , pp. B11-B15 (2004).		

Examiner Signature	<i>MPA</i>	Date Considered	12-20-2005
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